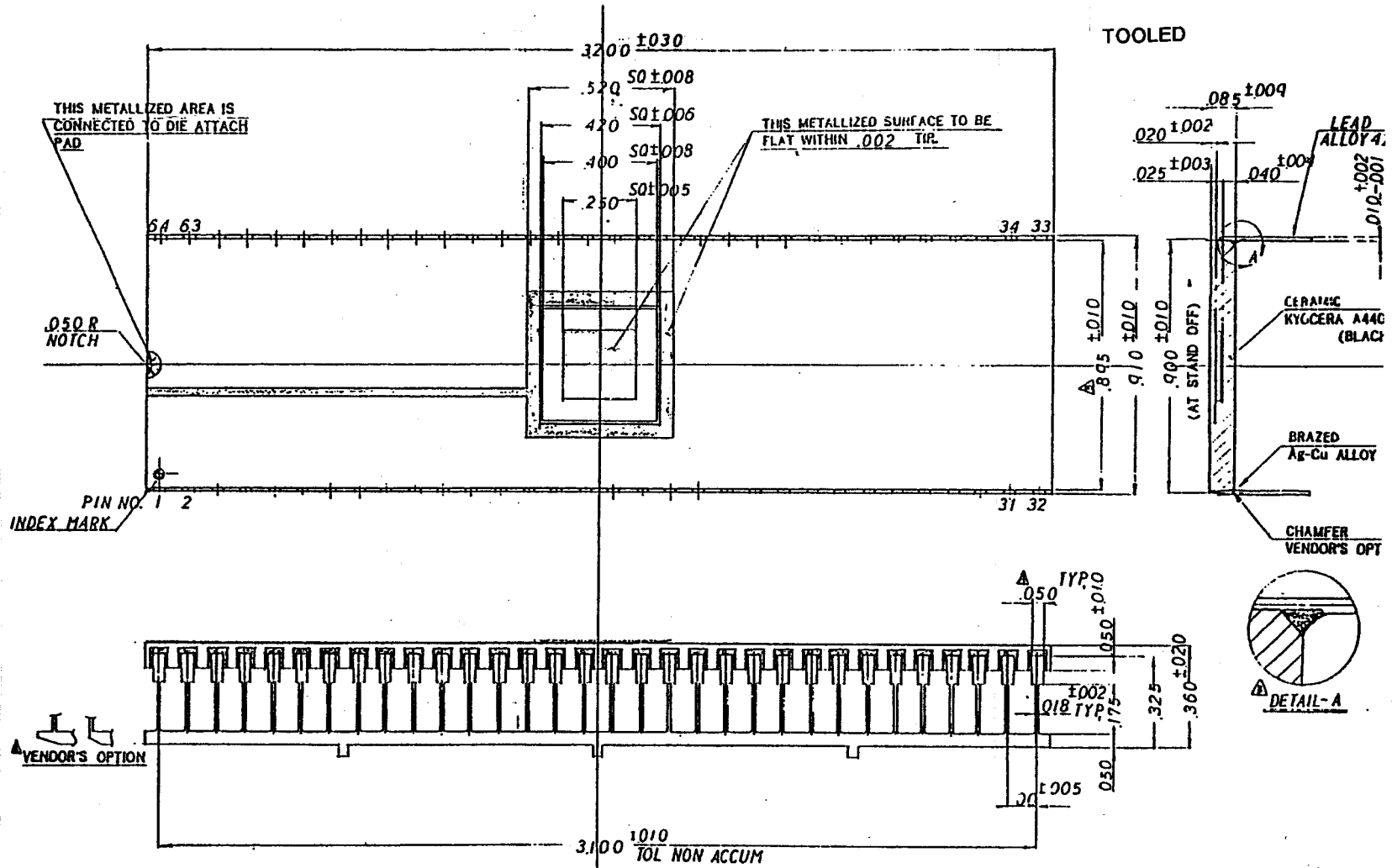


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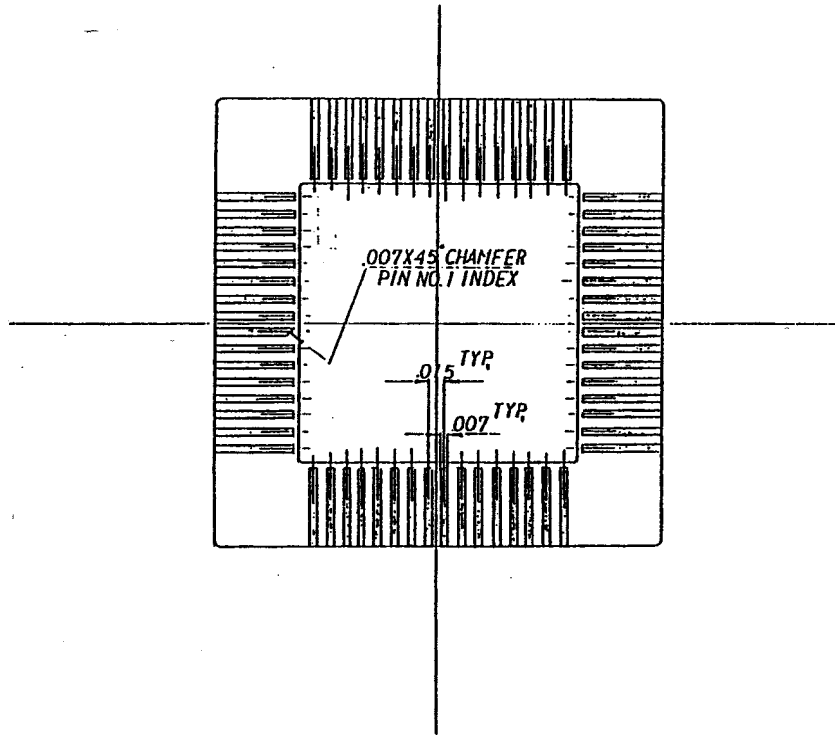


MODIFICATIONS A: CHANGED: LEAD FRAME, .890 → .895, ADDED: DETAIL-A B: CHANGED: .040 → .050, ADDED: VENDOR'S OPTION,				NAME 64 LEAD SIDE BRAZE PACKAGE		TOLERANCES UNLESS OTHERWISE SPECIFIED ±10% NLT. ±0.03		BPS-64SX- DRAWN <i>i. Ichijama</i> APPROVED <i>2004</i> DATE APR. 21	
CHANGE				SCALE 3:1		MATERIAL AS INDICATED		KYOTO CERAMIC CO., LTD. KYOTO JAPAN	
DATE SER21821 SER1082K				DRAWN CHECKED APPROVED		BWC NO KD-80178-B			



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BONDING PATTERN

NOTES

1. GOLD PLATING 60μ INCHES MIN THICKNESS OVER 100μ INCHES NOMINAL THICKNESS OF NICKEL. UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. LEAD RESISTANCE: 1.2 Ω MAX.
3. SEAL AREA TO BE METALLIZED
4. DIE ATTACH AREA TO BE METALLIZED
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

NAME 64 LEAD SIDE BRAZE PACKAGE		TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN C
SCALE 10:1	MATERIAL		APPROVED APL
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